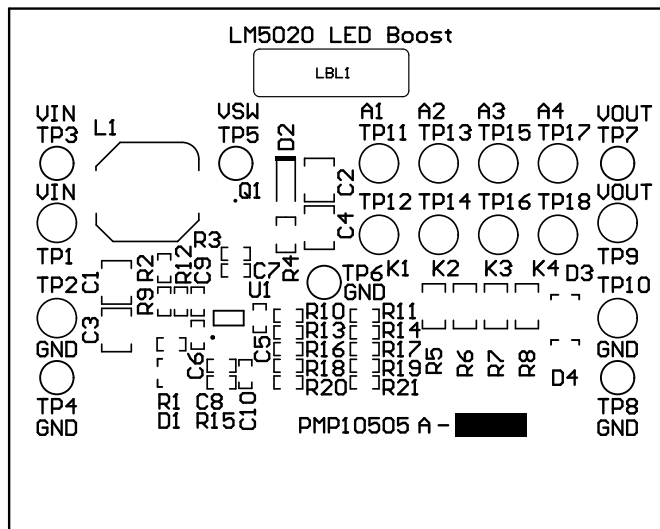
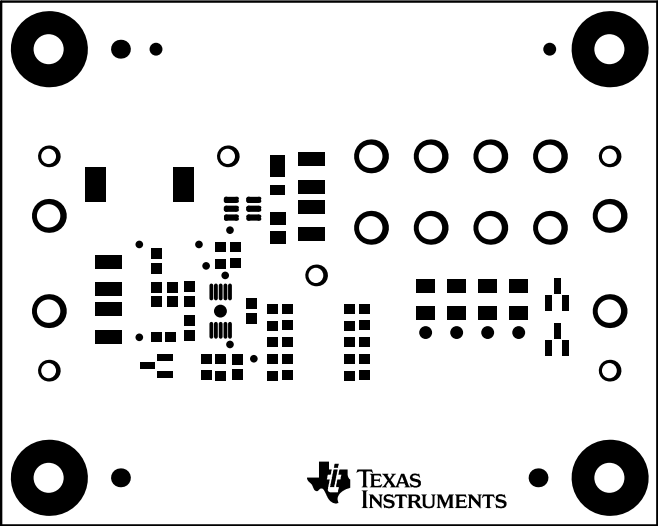
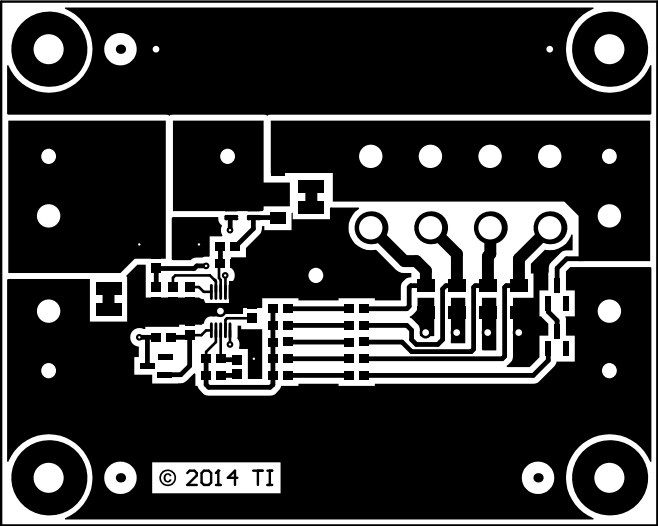




ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 7/11/2014 2:11:16 PM	TEXAS INSTRUMENTS	

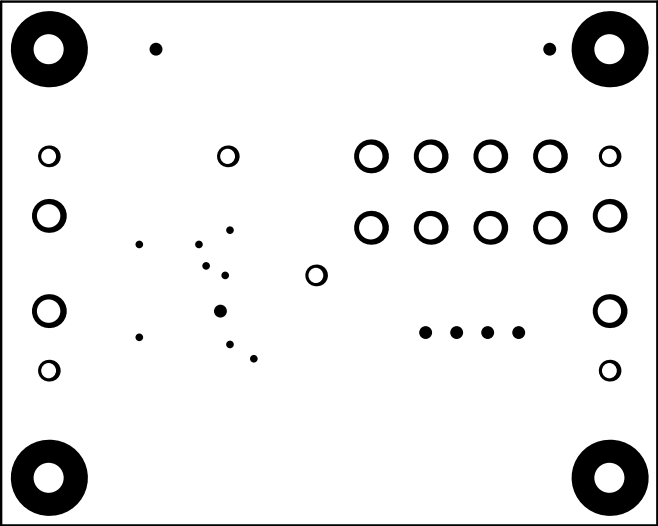


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 7/11/2014 2:11:17 PM	TEXAS INSTRUMENTS	

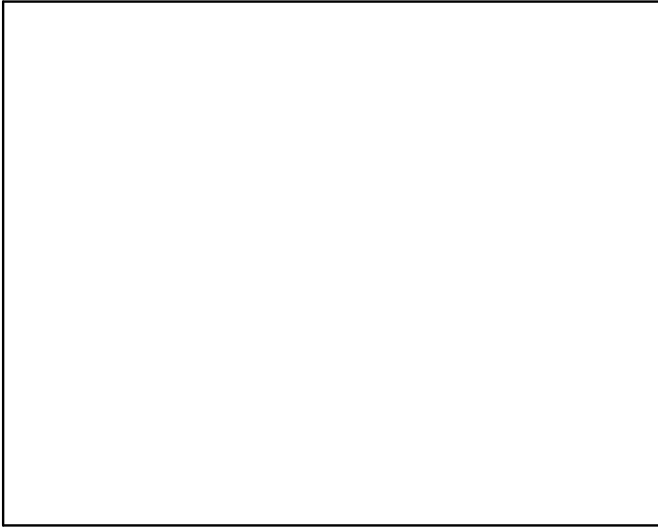


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 7/11/2014 2:11:18 PM	TEXAS INSTRUMENTS	

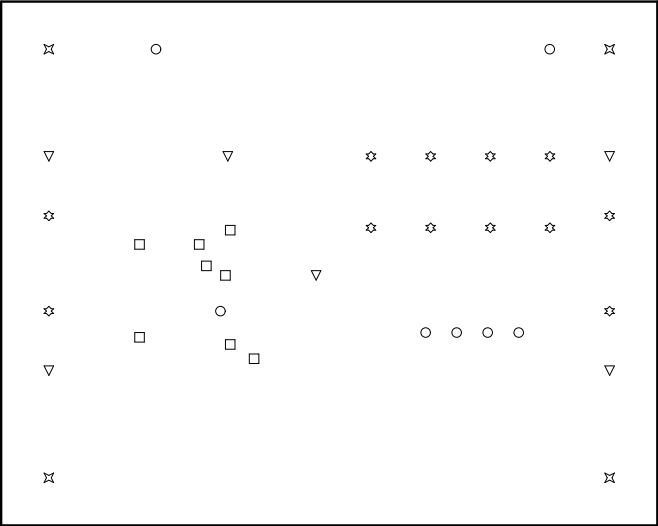
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 7/11/2014 2:11:19 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SVN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 7/11/2014 2:11:19 PM	TEXAS INSTRUMENTS	



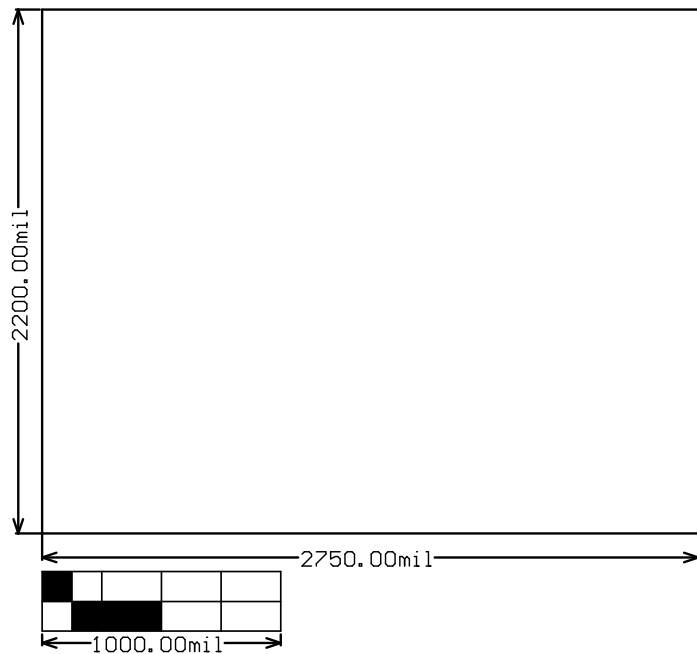
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 7/11/2014 2:11:20 PM		TEXAS INSTRUMENTS



Symbol	Hit Count	Tool Size	Plated	Hole Type
□	8	10mil (0.254mm)	PTH	Round
○	7	28mil (0.711mm)	PTH	Round
▽	6	63mil (1.6mm)	PTH	Round
☆	12	98.425mil (2.5mm)	PTH	Round
✕	4	125.984mil (3.2mm)	PTH	Round
	37 Total			

Drill Table

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 7/11/2014 2:11:21 PM		TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10505	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 7/11/2014 2:11:22 PM		TEXAS INSTRUMENTS

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